

TS4998

2 x 1W differential input stereo audio amplifier

Features

- Operating range from V_{CC}= 2.7V to 5.5V
- 1W output power per channel @ V_{CC}=5V, THD+N=1%, R_L=8Ω
- Ultra low standby consumption: 10nA typ.
- 80dB PSRR @ 217Hz with grounded inputs
- High SNR: 106dB(A) typ.
- Fast startup time: 45ms typ.
- Pop&click-free circuit
- Dedicated standby pin per channel
- Lead-free QFN16 4x4mm package

Applications

- Cellular mobile phones
- Notebook and PDA computers
- LCD monitors and TVs
- Portable audio devices

Description

The TS4998 is designed for top-class stereo audio applications. Thanks to its compact and power dissipation efficient QFN16 package with exposed pad, it suits a variety of applications.

With a BTL configuration, this audio power amplifier is capable of delivering 1W per channel of continuous RMS output power into an 8Ω load @ 5V.

Each output channel (left and right), also has its own external controlled standby mode pin to reduce the supply current to less than 10nA per channel. The device also features an internal thermal shutdown protection.

The gain of each channel can be configured by external gain setting resistors.



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Typical application schematics 1

Figure 1 shows a typical application for the TS4998 with a gain of +6dB set by the input resistors.



Typical application schematics Figure 1.

External component descriptions

Components	Functional description
R _{IN}	Input resistors that set the closed loop gain in conjunction with a fixed internal feedback resistor (Gain = R_{feed}/R_{IN} , where $R_{feed} = 50k\Omega$).
C _{IN}	Input coupling capacitors that block the DC voltage at the amplifier input terminal. Thanks to common mode feedback, these input capacitors are optional. However, if they are added, they form with R _{IN} a 1st order high pass filter with -3dB cut-off frequency ($f_{cut-off} = 1 / (2 \times \pi \times R_{IN} \times C_{IN})$).
C _S	Supply bypass capacitors that provides power supply filtering.
C _B	Bypass pin capacitor that provides half supply filtering.



2 Absolute maximum ratings

Table 2. Absolute maximum rating	Table 2.	Absolute	maximum	ratings
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Symbol	Parameter	Value	Unit
V _{CC}	Supply voltage ⁽¹⁾	6	V
V _{in}	Input voltage ⁽²⁾	GND to V _{CC}	V
T _{oper}	Operating free air temperature range	-40 to + 85	°C
T _{stg}	Storage temperature	-65 to +150	°C
Тj	Maximum junction temperature	150	°C
R _{thja}	Thermal resistance junction to ambient	120	°C'M'
Pd	Power dissipation	Internally limited	
ESD	Human body model ⁽³⁾ Digital pins STBYL, STBYR	15	kV
ESD	Machine model	200	V
	Latch-up immunity	200	mA

1. All voltage values are measured with respect to the ground p_{i} .

2. The magnitude of the input signal must never excee $1 \sqrt{c^2} \sim 0.3 \text{V} / \text{GND} - 0.3 \text{V}$.

3. All voltage values are measured from each $p_{\rm in}$ v ith respect to supplies.

Table 3.Operating conditions

	Symbol	Parameter	Value	Unit
	V _{CC}	Supply voltage	2.7 to 5.5	V
	V _{ICM} Common mode input voltage range G		GND to V _{CC} - 1V	V
	V _{Sʻi 3v}	Standoy voltage input: Device ON Device OFF	$1.3 \le V_{STBY} \le V_{CC}$ GND $\le V_{STBY} \le 0.4$	V
10	RL	Load resistor	≥ 4	Ω
$cO^{\prime\prime}$	R _{OUT} /GND	Output resistor to GND (V _{STBY} = GND)	≥ 1	MΩ
~05	TSD	Thermal shutdown temperature	150	°C
00	R _{thja}	Thermal resistance junction to ambient QFN16 ⁽¹⁾ QFN16 ⁽²⁾	45 85	°C/W

1. When mounted on a 4-layer PCB with vias.

2. When mounted on a 2-layer PCB with vias.



3 Electrical characteristics

Table 4.	$V_{CC} = +5V$, GND = 0V, T_{amb}	= 25°C (unless otherwise specified)
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Symbol	Parameter	Min.	Тур.	Max.	Unit
I _{CC}	Supply current No input signal, no load, left and right channel active		7.4	9.6	mA
I _{STBY}	Standby current ⁽¹⁾ No input signal, V_{STBYL} = GND, V_{STBYR} = GND, R_L = 8 Ω		10	2000	nA
V _{oo}	Output offset voltage No input signal, $R_L = 8\Omega$		1	35	mV
Po	Output power THD = 1% max, F = 1kHz, $R_L = 8\Omega$	800	1000	Ċ	SaW
THD + N	Total harmonic distortion + noise $P_o = 700 mW_{rms}$, G = 6dB, $R_L = 8\Omega$, 20Hz \leq F \leq 20kHz		0.5	No.	%
PSRR	Power supply rejection ratio ⁽²⁾ , inputs grounded $R_L = 8\Omega$, $G = 6dB$, $C_b = 1\mu$ F, $V_{ripple} = 200mV_{pp}$ F = 217Hz F = 1kHz	Pe,	80 75		dB
CMRR	Common mode rejection ratio ⁽³⁾ $R_L = 8\Omega$, $G = 6dB$, $C_b = 1\mu$ F, $V_{incm} = 200$ mV _{PL} F = 217Hz F = 1kHz		57 57		dB
SNR	Signal-to-noise ratio A-weighted, G = 6dB, C _b = ${}^{+}\mu$, R _L = 8Ω (THD + N ≤ 0.5%, 20Hz < F < 20kHz)		108		dB
Crosstalk	Channel separatic n, $R_L = 8\Omega$, G = 6dB F = 1kHz F = 2vHz to 20kHz		105 80		dB
V _N	Our put voltage noise, F = 20Hz to 20kHz, $R_L = 8\Omega$, G=6dB $D_5 = 1\mu F$ Unweighted A-weighted		15 10		µVrms
Gain	Gain value (R _{IN} in kΩ)	$\frac{40 k\Omega}{R_{\rm IN}}$	$\frac{50 k\Omega}{R_{\rm IN}}$	$\frac{60k\Omega}{R_{\rm IN}}$	V/V
t _{WU}	Wake-up time (C _b = 1µF)		46		ms
t _{STBY}	Standby time ($C_b = 1\mu F$)		10		μs
Φ _M	Phase margin at unity gain $R_L = 8\Omega$, $C_L = 500 pF$		65		Degrees
GM	Gain margin, $R_L = 8\Omega$, $C_L = 500$ pF		15		dB
GBP	Gain bandwidth product, $R_L = 8\Omega$		1.5		MHz

1. Standby mode is active when $V_{\mbox{STBY}}$ is tied to GND.

2. Dynamic measurements - $20*log(rms(V_{out})/rms(V_{ripple}))$. V_{ripple} is the sinusoidal signal superimposed upon V_{CC} .

3. Dynamic measurements - $20*log(rms(V_{out})/rms(V_{incm}))$.



Symbol	Parameter	Min.	Тур.	Max.	Unit
I _{CC}	Supply current No input signal, no load, left and right channel active		6.6	8.6	mA
I _{STBY}	Standby current ⁽¹⁾ No input signal, V_{STBYL} = GND, V_{STBYR} = GND, R_L = 8 Ω		10	2000	nA
V _{oo}	Output offset voltage No input signal, $R_L = 8\Omega$		1	35	mV
Po	Output power THD = 1% max, F = 1kHz, $R_L = 8\Omega$	370	460		mW
THD + N	Total harmonic distortion + noise $P_0 = 300 \text{mW}_{rms}, \text{ G} = 6 \text{dB}, \text{ R}_L = 8\Omega, 20 \text{Hz} \leq F \leq 20 \text{kHz}$		0.5		6 %
PSRR	Power supply rejection ratio ⁽²⁾ , inputs grounded $R_L = 8\Omega$, $G = 6dB$, $C_b = 1\mu$ F, $V_{ripple} = 200mV_{pp}$ F = 217Hz F = 1kHz	Q	30 75	JC	dB
CMRR	Common mode rejection ratio ⁽³⁾ $R_L = 8\Omega$, $G = 6dB$, $C_b = 1\mu F$, $V_{incm} = 200mV_{pp}$ F = 217Hz F = 1kHz	e	57 57		dB
SNR	Signal-to-noise ratio A-weighted, G = 6dB, $C_b = 1\mu$ F, $R_L = 8\Omega$ (THD + N ≤0.5%, 20Hz < F < 20kHz)		104		dB
Crosstalk	Channel separation, $R_L = 8\Omega$, $G = 603$ F = 1kHz F = 20Hz to 20kHz		105 80		dB
V _N	Output voltage no.se. F = 20Hz to 20kHz, $R_L = 8\Omega$, G=6dB $C_b = 1\mu F$ Unweighted A-v.eighted		15 10		μVrms
Gain	Cain value (R_{IN} in $k\Omega$)	$\frac{40 k\Omega}{R_{\rm IN}}$	$\frac{50 k\Omega}{R_{\rm IN}}$	60 κΩ ^R IN	V/V
Tw.U	Wake-up time (C _b = 1µF)		47		ms
t _{STBY}	Standby time ($C_b = 1\mu F$)		10		μs
Φ _M	Phase margin at unity gain $R_L = 8\Omega$, $C_L = 500 pF$		65		Degrees
GM	Gain margin, $R_L = 8\Omega$, $C_L = 500 pF$		15		dB
GBP	Gain bandwidth product, $R_L = 8\Omega$		1.5		MHz

Table 5. V_{CC} = +3.3V, GND = 0V, T_{amb} = 25°C (unless otherwise specified)

1. Standby mode is active when $V_{\mbox{\scriptsize STBY}}$ is tied to GND.

2. Dynamic measurements - $20*\log(rms(V_{out})/rms(V_{ripple}))$. V_{ripple} is the sinusoidal signal superimposed upon V_{CC} .

3. Dynamic measurements - $20*log(rms(V_{out})/rms(V_{incm}))$.

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Symbol	Parameter	Min.	Тур.	Max.	Unit
I _{CC}	Supply current No input signal, no load, left and right channel active		6.2	8.1	mA
I _{STBY}	Standby current ⁽¹⁾ No input signal, V_{STBYL} = GND, V_{STBYR} = GND, R_L = 8 Ω		10	2000	nA
V _{oo}	Output offset voltage No input signal, $R_L = 8\Omega$		1	35	mV
Po	Output power THD = 1% max, F = 1kHz, $R_L = 8\Omega$	220	295		mW
THD + N	Total harmonic distortion + noise $P_o = 200mW_{rms}, G = 6dB, R_L = 8\Omega, 20Hz \le F \le 20kHz$		0.5		6%
PSRR	Power supply rejection ratio ⁽²⁾ , inputs grounded $R_L = 8\Omega$, $G = 6dB$, $C_b = 1\mu$ F, $V_{ripple} = 200mV_{pp}$ F = 217Hz F = 1kHz	0	70 /3	JUC	dB
CMRR	Common mode rejection ratio ⁽³⁾ $R_L = 8\Omega$, $G = 6dB$, $C_b = 1\mu F$, $V_{incm} = 200mV_{pp}$ F = 217Hz F = 1kHz	er	57 57		dB
SNR	Signal-to-noise ratio A-weighted, G = 6dB, C _b = 1 μ F, R _L = 8 Ω (THD + N ≤ 0.5%, 20Hz < F < 20kHz)		102		dB
Crosstalk	Channel separation, $R_L = 8\Omega$, $G = 603$ F = 1kHz F = 20Hz to 20kHz		105 80		dB
V _N	Output voltage no.se. F = 20Hz to 20kHz, $R_L = 8\Omega$, G=6dB $C_b = 1\mu F$ Unweighted A-weighted		15 10		μVrms
Gain	Cain value (R_{IN} in $k\Omega$)	$\frac{40k\Omega}{R_{\rm IN}}$	$\frac{50k\Omega}{R_{\rm IN}}$	$\frac{60k\Omega}{R_{\rm IN}}$	V/V
Tw,U	Wake-up time (C _b = 1µF)		46		ms
t _{STBY}	Standby time ($C_b = 1\mu F$)		10		μs
Φ_{M}	Phase margin at unity gain $R_L = 8\Omega$, $C_L = 500 pF$		65		Degrees
GM	Gain margin, $R_L = 8\Omega$, $C_L = 500 pF$		15		dB
GBP	Gain bandwidth product, $R_L = 8\Omega$		1.5		MHz

Table 6.	V _{CC} = +2.7V, GND = 0V, T _{amb} = 2	5°C (unless otherwise specified)
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1. Standby mode is active when $V_{\mbox{STBY}}$ is tied to GND.

2. Dynamic measurements - $20*log(rms(V_{out})/rms(V_{ripple}))$. V_{ripple} is the sinusoidal signal superimposed upon V_{CC} .

3. Dynamic measurements - $20*log(rms(V_{out})/rms(V_{incm}))$.

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Figure 36. CMRR vs. common mode input W. itr.ge



Figure 37. Crosstalk vs. frequency



Figure 33. CMRR vs. frequency













Vcc = 5V

G = +6dB

Tamb = 25°C

1

1000

100

10

1

0.1

0.01

1E-3

0

(Vool (mV)







Figure 46. Differential DC output voltage vs. common mode input voltage





Figure 48. Differential DC output voltage vs.

2

3

Commor N ode Input Voltage (V)

4

5

Figure 49. Current consumption vs. power supply voltage



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Vool (mV)







Figure 50. Current consumption vs. standby voltage



Figure 52. Current consumption vs. standby voltage

Figure 53. Standby current vs. power supply voltage









Figure 60. **Power dissipation vs. output power Figure 61.** Power dissipation vs. output power





Figure 62. Power dissipation vs. output power Figure 63. Power derating curves



4 Application information

4.1 General description

The TS4998 integrates two monolithic full-differential input/output power amplifiers with two selectable standby pins dedicated for each channel. The gain of each channel is set by external input resistors.

4.2 Differential configuration principle

The TS4998 also includes a common mode feedback loop that controls the output bias value to average it at $V_{CC}/2$ for any DC common mode input voltage. This allows maximum output voltage swing, and therefore, to maximize the output power. Moreover, as the load is connected differentially instead of single-ended, output power is four times higher for the same power supply voltage.

The advantages of a full-differential amplifier are:

- High PSRR (power supply rejection ratio),
- High common mode noise rejection,
- Virtually no pops&clicks without additional circuit, y, giving a faster startup time compared to conventional single-ended input amplifiers,
- Easier interfacing with differential output audio DAC,
- No input coupling capacitors req lire/J due to common mode feedback loop.

In theory, the filtering of the internal bias by an external bypass capacitor is not necessary. However, to reach maximum performance in all tolerance situations, it is recommended to keep this option.

The only constraint is that the differential function is directly linked to external resistor mismatching, therefore you must pay particular attention to this mismatching in order to obtain the best performance from the amplifier.

4.3 Clain in typical application schematic

A typical differential application is shown in Figure 1 on page 3.

The value of the differential gain of each amplifier is dependent on the values of external input resistors R_{IN1} to R_{IN4} and of integrated feedback resistors with fixed value. In the flat region of the frequency-response curve (no C_{IN} effect), the differential gain of each channel is expressed by the relation given in *Equation 1*.

Equation 1

$$A_{V_{diff}} = \frac{V_{O+} - V_{O-}}{Diff_{input+} - Diff_{input-}} = \frac{R_{feed}}{R_{IN}} = \frac{50k\Omega}{R_{IN}}$$

where $R_{IN} = R_{IN1} = R_{IN2} = R_{IN3} = R_{IN4}$ expressed in k Ω and $R_{feed} = 50$ k Ω (value of internal feedback resistors).



Due to the tolerance on the internal 50k Ω feedback resistors, the differential gain will be in the range (no tolerance on R_{IN}):

$$\frac{40k\Omega}{R_{IN}} {\leq} A_{V_{diff}} {\leq} \frac{60k\Omega}{R_{IN}}$$

The difference of resistance between input resistors of each channel have direct influence on the PSRR, CMRR and other amplifier parameters. In order to reach maximum performance, we recommend matching the input resistors R_{IN1} , R_{IN2} , R_{IN3} , and R_{IN4} with a maximum tolerance of 1%.

Note:

For the rest of this section, Av_{diff} will be called A_V to simplify the mathematical expressions.

4.4 Common mode feedback loop limitations

As explained previously, the common mode feedback loop allows the output E/C bias voltage to be averaged at $V_{CC}/2$ for any DC common mode bias input voltage.

Due to the V_{ICM} limitation of the input stage (see *Table 3 on page 4*), the common mode feedback loop can fulfil its role only within the defined range. This range depends upon the values of V_{CC}, R_{IN} and R_{feed} (A_V). To have a good estimation of the V_{ICM} value, use the following formula:

Equation 2

$$V_{\text{ICM}} = \frac{V_{\text{CC}} \times R_{\text{IN}} + 2 \times V_{\text{c}} \times S_{\text{i} \neq \text{ed}}}{2 \times (R_{\text{IN}} + R_{\text{feeu}'})} = \frac{V_{\text{CC}} \times R_{\text{IN}} + 2 \times V_{\text{ic}} \times 50 \text{k}\Omega}{2 \times (R_{\text{IN}} + 50 \text{k}\Omega)} (V)$$

with V_{CC} in volts, R_{IN} in k Ω and

$$V_{ic} = \frac{\text{Diff}_{input+} + \text{Diff}_{input-}}{2} \qquad (V)$$

The result of the calculation must be in the range:

$$\text{GND} \leq V_{\text{ICM}} \leq V_{\text{CC}} - 1V$$

Due to the +/-20% tolerance on the 50k Ω feedback resistors R_{feed} (no tolerance on R_{IN}), it is also important to check that the V_{ICM} remains in this range at the tolerance limits:

$$\frac{\mathsf{V}_{\mathsf{CC}} \times \mathsf{R}_{\mathsf{IN}} + 2 \times \mathsf{V}_{\mathsf{ic}} \times 40 \mathsf{k}\Omega}{2 \times (\mathsf{R}_{\mathsf{IN}} + 40 \mathsf{k}\Omega)} \leq \mathsf{V}_{\mathsf{ICM}} \leq \frac{\mathsf{V}_{\mathsf{CC}} \times \mathsf{R}_{\mathsf{IN}} + 2 \times \mathsf{V}_{\mathsf{ic}} \times 60 \mathsf{k}\Omega}{2 \times (\mathsf{R}_{\mathsf{IN}} + 60 \mathsf{k}\Omega)} (\mathsf{V})$$

If the result of the $V_{\mbox{\scriptsize ICM}}$ calculation is not in this range, an input coupling capacitor must be used.

Example: $V_{CC} = 2.7V$, $A_V = 2$, and $V_{ic} = 2.2V$.

With internal resistors $R_{feed} = 50k\Omega$, calculated external resistors are $R_{IN} = R_{feed}/A_V = 25k\Omega$, $V_{CC} = 2.7V$ and $V_{ic} = 2.2V$, which gives $V_{ICM} = 1.92V$. Taking into account the tolerance on the feedback resistors, with $R_{feed} = 40k\Omega$ the common mode input voltage is $V_{ICM} = 1.87V$ and with $R_{feed} = 60k\Omega$ it is $V_{ICM} = 1.95V$.

These values are not in range from GND to V_{CC} - 1V = 1.7V, therefore input coupling capacitors are required. Alternatively, you can change the V_{ic} value.



4.5 Low frequency response

The input coupling capacitors block the DC part of the input signal at the amplifier inputs. In the low frequency region, C_{IN} starts to have an effect. C_{IN} and R_{IN} form a first-order high pass filter with a -3dB cut-off frequency.

$$F_{CL} = \frac{1}{2 \times \pi \times R_{IN} \times C_{IN}} (Hz)$$

with R_{IN} expressed in Ω and C_{IN} expressed in F.

So, for a desired -3dB cut-off frequency we can calculate C_{IN}:

$$C_{IN} = \frac{1}{2 \times \pi \times R_{IN} \times F_{CL}}(F)$$

From *Figure 64*, you can easily establish the C_{IN} value required for a -3 dB cut-off frequency for some typical cases.





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Power dissipation and efficiency 4.6

Assumptions:

- Load voltage and current are sinusoidal (V_{out} and I_{out})
- Supply voltage is a pure DC source (V_{CC})

The output voltage is:

$$V_{out} = V_{peak} \sin \omega t$$
 (V)

and

$$I_{out} = \frac{V_{out}}{R_L}$$
 (A)

and

$$\mathsf{P}_{\mathsf{out}} = \frac{\mathsf{V}_{\mathsf{peak}}^2}{2\mathsf{R}_{\mathsf{L}}} \; (\mathsf{W})$$

roductls Therefore, the average current delivered by the supply voltage is:

Equation 3

$$I_{ccl.VG} = 2 \frac{v_{r,cak}}{\pi R_L} (A)$$

The power delivered by the supply voltage is:

Equation 4

$$P_{supply} = V_{CC} I_{ccAVG} (W)$$

Therefore, the nower dissipated by each amplifier is:

 $P_{c'ss} = P_{supply} - P_{out} (W)$

$$\mathsf{P}_{\mathsf{diss}} = \frac{2\sqrt{2}\mathsf{V}_{\mathsf{CC}}}{\pi_{\mathsf{v}}/\mathsf{R}_{\mathsf{I}}}\sqrt{\mathsf{P}_{\mathsf{out}}} - \mathsf{P}_{\mathsf{out}}(\mathsf{W})$$

psolete and the maximum value is obtained when:

$$\frac{\partial \mathsf{Pdiss}}{\partial \mathsf{P}_{\mathsf{out}}} = 0$$

and its value is:

Equation 5

$$Pdissmax = \frac{2 Vcc^2}{\pi^2 R_L} (W)$$

Note:

This maximum value is only dependent on the power supply voltage and load values.



The efficiency is the ratio between the output power and the power supply:

Equation 6

$$\eta = \frac{P_{out}}{P_{supply}} = \frac{\pi V_{peak}}{4Vcc}$$

The maximum theoretical value is reached when V_{peak} = V_{CC}, so:

$$\eta = \frac{\pi}{4} = 78.5\%$$

The TS4998 is stereo amplifier so it has two power amplifiers. Each amplifier produces heat due to its power dissipation. Therefore, the maximum die temperature is the sum of each amplifier's maximum power dissipation. It is calculated as follows:

- $P_{diss,1}$ = Power dissipation of left channel power amplifier
- $P_{diss,2}$ = Power dissipation of right channel power amplifier
- Total $P_{diss} = P_{diss 1} + P_{diss 2}$ (W)

In most cases, $P_{diss,1} = P_{diss,2}$, giving:

issipation of left channel power amplifier
issipation of right channel power amplifier

$$_{1} + P_{diss 2} (W)$$

 $= P_{diss 2}, \text{ giving:}$
TotalP_{diss} = 2 × P_{diss1} = $\frac{4\sqrt{2}V_{CC}}{\pi\sqrt{R}}\sqrt{F_{out}}-2P_{out}(W)$

The maximum die temperature allowable for the 154998 is 150°C. In case of overheating, a thermal shutdown protection set to 150°C, puts the TS4998 in standby until the temperature of the die is reduced by about 5°C.

To calculate the maximum ambient temperature T_{amb} allowable, you need to know:

- the power supply voltage value, V_{CC}
- the load resistor value, RI
- the package ivee, R_{THJA}

Example: V_{CC}-5V, R_I=8Ω, R_{THJA}QFN16=85°C/W (with 2-layer PCB with vias).

Using the power dissipation formula given in *Equation 5*, the maximum dissipated power per channel is:

 $P_{dissmax} = 633 mW$

And the power dissipated by both channels is:

Total P_{dissmax} = 2 x P_{dissmax} = 1266mW

Tamb is calculated as follows:

Equation 7

$$T_{amb} = 150^{\circ} C - R_{TJHA} \times TotalP_{dissmax}$$

Therefore, the maximum allowable value for T_{amb} is:

T_{amb} = 150 - 85 x 2 x 1.266=42.4°C

If a 4-layer PCB with vias is used, R_{THJA}QFN16 = 45°C/W and the maximum allowable value for $T_{\mbox{\scriptsize amb}}$ in this case is:

 $T_{amb} = 150 - 45 \times 2 \times 1.266 = 93^{\circ}C$





4.7 Footprint recommendation

Footprint soldering pad dimensions are given in Figure 72 on page 30. As discussed in the previous section, the maximum allowable value for ambient temperature is dependent on the thermal resistance junction to ambient R_{THJA} . Decreasing the R_{THJA} value causes better power dissipation.

Based on best thermal performance, it is recommended to use 4-layer PCBs with vias to effectively remove heat from the device. It is also recommended to use vias for 2-layer PCBs to connect the package exposed pad to heatsink cooper areas placed on another layer.

For proper thermal conductivity, the vias must be plated through and solder-filled. Typical thermal vias have the following dimensions: 1.2mm pitch, 0.3mm diameter.



QFN16 footprint recommendation Figure 65.

Decoupling of the circuit 4.8

Two capacitors are needed to correctly bypass the TS4998: a power supply bypass copacitor C_S and a bias voltage bypass capacitor C_b.

The C_S capacitor has particular influence on the THD+N at high frequencies (above 7kHz) and an indirect influence on power supply disturbances. With a value for C_S of 1µF, one can expect THD+N performance similar to that shown in the datasheet.

In the high frequency region, if C_S is lower than 1µF, then THD+N increases and disturbances on the power supply rail are less filtered.

On the other hand, if C_S is greater than 1µF, then those disturbances on the power supply rail are more filtered.

The C_b capacitor has an influence on the THD+N at lower frequencies, but also impacts PSRR performance (with grounded input and in the lower frequency region).



4.9 Standby control and wake-up time t_{WU}

The TS4998 has two dedicated standby pins (STBYL, STBYR). These pins allow to put each channel in standby mode or active mode independently. The amplifier is designed to reach close to zero pop when switching from one mode to the other.

When both channels are in standby ($V_{STBYL} = V_{STBYR} = GND$), the circuit is in shutdown mode. When at least one of the two standby pins is released to put the device ON, the bypass capacitor C_b starts to be charged. Because C_b is directly linked to the bias of the amplifier, the bias will not work properly until the C_b voltage is correct. The time to reach this voltage is called the wake-up time or t_{WU} and is specified in *Table 4 on page 5*, with $C_b=1\mu F$.

During the wake-up phase, the TS4998 gain is close to zero. After the wake-up time, the gain is released and set to its nominal value. If C_b has a value different from 1µF, then refer to the graph in *Figure 66* to establish the corresponding wake-up time.

When a channel is set to standby mode, the outputs of this channel are in high impedance state.



Figure 66. Typical startup time vs. bypass capacitor

4.10 Shutdown time

When the standby command is activated (both channels put into standby mode), the time required to put the two output stages of each channel in high impedance and the internal circuitry in shutdown mode is a few microseconds.

Note: In shutdown mode when both channels are in standby, the Bypass pin and L_{IN} +, L_{IN} -, R_{IN} +, R_{IN} - pins are shorted to ground by internal switches. This allows a quick discharge of C_b and C_{IN} capacitors.

4.11 Pop performance

Due to its fully differential structure, the pop performance of the TS4998 is close to perfect. However, due to mismatching between internal resistors R_{feed} , external resistors R_{IN} and



external input capacitors C_{IN} , some noise might remain at startup. To eliminate the effect of mismatched components, the TS4998 includes pop reduction circuitry. With this circuitry, the TS4998 is close to zero pop for all possible common applications.

In addition, when the TS4998 is in standby mode, due to the high impedance output stage in this configuration, no pop is heard.

4.12 Single-ended input configuration

It is possible to use the TS4998 in a single-ended input configuration. However, input coupling capacitors are needed in this configuration. The schematic diagram in *Figure 67* shows an example of this configuration for a gain of +6dB set by the input resistors.

Figure 67. Typical single-ended input application



The component calculations remain the same for the gain. In single-ended input configuration, the formula is:

$$Av_{SE} = \frac{V_{O+} - V_{O-}}{V_e} = \frac{R_{feed}}{R_{IN}} = \frac{50k\Omega}{R_{IN}}$$

with R_{IN} expressed in $k\Omega$



4.13 Notes on PSRR measurement

What is the PSRR?

The PSRR is the power supply rejection ratio. The PSRR of a device is the ratio between a power supply disturbance and the result on the output. In other words, the PSRR is the ability of a device to minimize the impact of power supply disturbance to the output.

How is the PSRR measured?

The PSRR is measured as shown in Figure 68.

Figure 68. PSRR measurement



Principles of operation

- The DC voltage supply (V_{CC}) is fixed
- The AC sinusoidal ripple voltage (V_{ripple}) is fixed
- No bypass capacitor C_S is used

The PSRR value for each frequency is calculated as:

$$PSRR = 20 \times Log \left[\frac{RMS_{(Output)}}{RMS_{(Vripple)}} \right] (dB)$$

RMS is an rms selective measurement.



5 QFN16 package information

In order to meet environmental requirements, STMicroelectronics offers these devices in ECOPACK[®] packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an STMicroelectronics trademark. ECOPACK specifications are available at: <u>www.st.com</u>.





Figure 70. QFN16 pinout (top viev/)



	Dimensions			
	Def	Millimeters (mm)		
	Ref	Min	Тур	Мах
	Α	0.8	0.9	1.0
	A1		0.02	0.05
$\stackrel{E}{\longleftrightarrow} \stackrel{A}{\longleftrightarrow} \stackrel{K}{\longleftrightarrow} \stackrel{E2}{\longleftrightarrow}$	A3		0.20	
→ ← A1	b	0.18	0.25	0.30
	D	3.85	4.0	1. 5
	D2	2.1	100	2.6
↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓	E	5.25	4.0	4.15
	E2	2.1		2.6
* The Exposed Pad is connected to Ground.	e		0.65	
colo	к	0.2		
005	L	0.30	0.40	0.50
	r	0.11		

Figure 71. QFN16 4x4mm package mechanical data







6 Ordering information

Table 8. Order codes

Order code	Temperature range	Package	Packaging	Marking
TS4998IQT -40°C to +85°C		QFN16 4x4mm	Tape & reel	K998

obsolete Product(s) - Obsolete Product(s)

7 Revision history

Table 9.Document revision history

Date	Revision	Changes
20-Dec-2007	1	Initial release.

obsolete Product(s). Obsolete Product(s)

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